



PSMN3R3-80BS

N-channel 80 V, 3.5 mΩ standard level MOSFET in D2PAK

Rev. 2 — 29 February 2012

Product data sheet

1. Product profile

1.1 General description

Standard level N-channel MOSFET in D2PAK package qualified to 175°C. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

1.2 Features and benefits

- High efficiency due to low switching and conduction losses
- Suitable for standard level gate drive

1.3 Applications

- DC-to-DC converters
- Motor control
- Load switch
- Server power supplies

1.4 Quick reference data

Table 1. Quick reference data

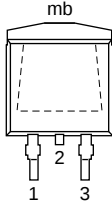
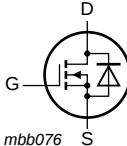
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C	-	-	80	V
I _D	drain current	T _{mb} = 25 °C; V _{GS} = 10 V; see Figure 1	^[1] -	-	120	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; see Figure 2	-	-	306	W
T _j	junction temperature		-55	-	175	°C
Static characteristics						
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C; see Figure 13	-	3	3.5	mΩ
		V _{GS} = 10 V; I _D = 25 A; T _j = 100 °C; see Figure 12 ; see Figure 13	-	4.95	5.8	mΩ
Dynamic characteristics						
Q _{GD}	gate-drain charge	V _{GS} = 10 V; I _D = 75 A; V _{DS} = 40 V; see Figure 14 ; see Figure 15	-	28	-	nC
Q _{G(tot)}	total gate charge		-	111	-	nC
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	V _{GS} = 10 V; T _{j(init)} = 25 °C; I _D = 120 A; V _{sup} ≤ 80 V; R _{GS} = 50 Ω; unclamped	-	-	676	mJ

[1] Continuous current is limited by package.



2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	D	drain		
3	S	source		
mb	D	drain		

SOT404 (D2PAK)

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN3R3-80BS	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

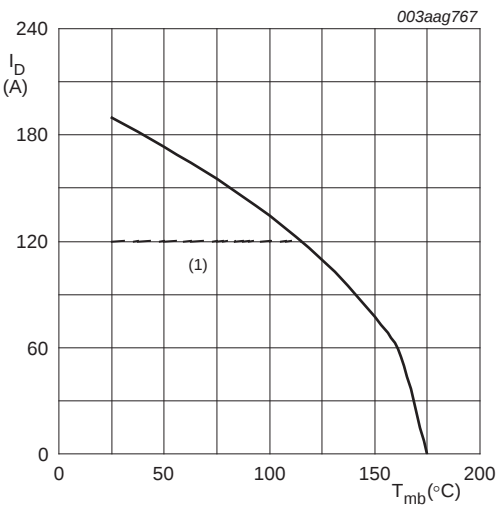
4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

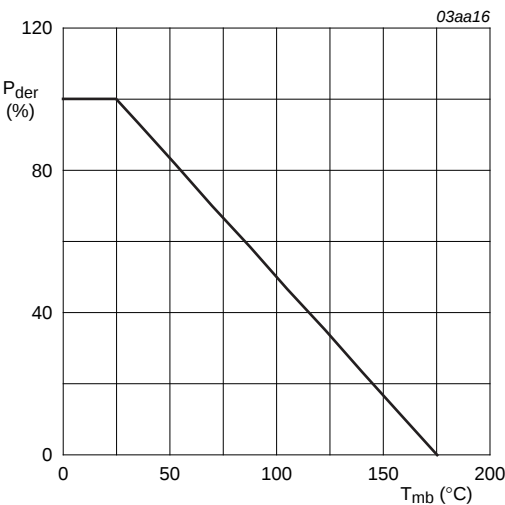
Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C	-	80	V
V _{DGR}	drain-gate voltage	T _j ≥ 25 °C; T _j ≤ 175 °C; R _{GS} = 20 kΩ	-	80	V
V _{GS}	gate-source voltage		-20	20	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 100 °C; see Figure 1	[1] -	120	A
		V _{GS} = 10 V; T _{mb} = 25 °C; see Figure 1	[1] -	120	A
I _{DM}	peak drain current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C; see Figure 3	-	760	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; see Figure 2	-	306	W
T _{stg}	storage temperature		-55	175	°C
T _j	junction temperature		-55	175	°C
T _{sld(M)}	peak soldering temperature		-	260	°C
Source-drain diode					
I _S	source current	T _{mb} = 25 °C	[1] -	120	A
I _{SM}	peak source current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C	-	760	A
Avalanche ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	V _{GS} = 10 V; T _{j(init)} = 25 °C; I _D = 120 A; V _{sup} ≤ 80 V; R _{GS} = 50 Ω; unclamped	-	676	mJ

[1] Continuous current is limited by package.



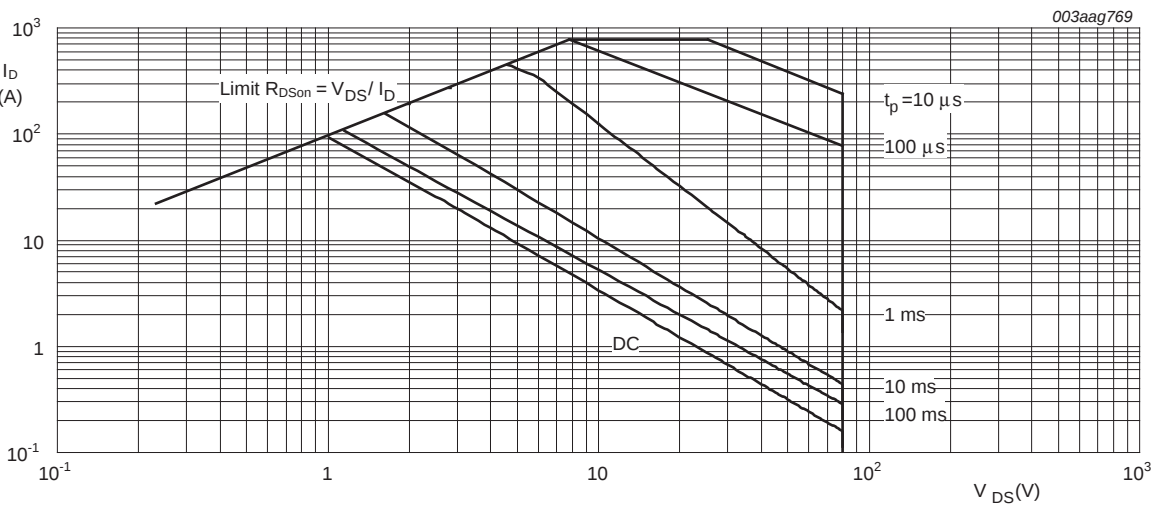
$V_{GS} \geq 10$ V; (1) Capped at 120 A due to package

Fig 1. Continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100 \%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



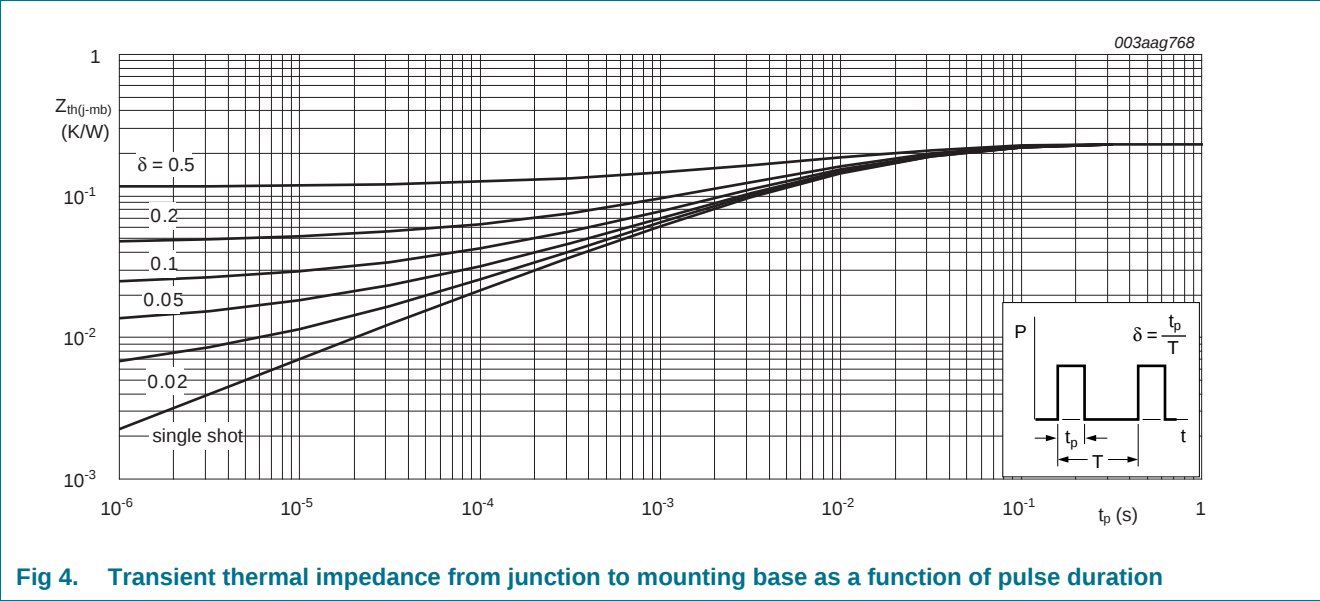
$T_{mb} = 25^{\circ}C$; I_{DM} is a single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	0.22	0.49	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	minimum footprint; mounted on a printed circuit board	-	50	-	K/W



6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\ \mu A$; $V_{GS} = 0\ V$; $T_j = -55\ ^\circ C$	73	-	-	V
		$I_D = 250\ \mu A$; $V_{GS} = 0\ V$; $T_j = 25\ ^\circ C$	80	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\ mA$; $V_{DS} = V_{GS}$; $T_j = 175\ ^\circ C$; see Figure 10	1	-	-	V
		$I_D = 1\ mA$; $V_{DS} = V_{GS}$; $T_j = -55\ ^\circ C$; see Figure 10	-	-	4.6	V
		$I_D = 1\ mA$; $V_{DS} = V_{GS}$; $T_j = 25\ ^\circ C$; see Figure 10 ; see Figure 11	2	3	4	V
I_{DSS}	drain leakage current	$V_{DS} = 80\ V$; $V_{GS} = 0\ V$; $T_j = 25\ ^\circ C$	-	0.02	10	μA
		$V_{DS} = 80\ V$; $V_{GS} = 0\ V$; $T_j = 175\ ^\circ C$	-	-	500	μA
I_{GSS}	gate leakage current	$V_{GS} = -20\ V$; $V_{DS} = 0\ V$; $T_j = 25\ ^\circ C$	-	10	100	nA
		$V_{GS} = 20\ V$; $V_{DS} = 0\ V$; $T_j = 25\ ^\circ C$	-	10	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\ V$; $I_D = 25\ A$; $T_j = 175\ ^\circ C$; see Figure 12 ; see Figure 13	-	7.1	8.4	mΩ
		$V_{GS} = 10\ V$; $I_D = 25\ A$; $T_j = 25\ ^\circ C$; see Figure 13	-	3	3.5	mΩ
		$V_{GS} = 10\ V$; $I_D = 25\ A$; $T_j = 100\ ^\circ C$; see Figure 12 ; see Figure 13	-	4.95	5.8	mΩ
R_G	internal gate resistance (AC)	$f = 1\ MHz$	-	0.9	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 0\ A$; $V_{DS} = 0\ V$; $V_{GS} = 10\ V$	-	104	-	nC
		$I_D = 75\ A$; $V_{DS} = 40\ V$; $V_{GS} = 10\ V$; see Figure 14 ; see Figure 15	-	111	-	nC
Q_{GS}	gate-source charge		-	38	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	24	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	14	-	nC
Q_{GD}	gate-drain charge		-	28	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 75\ A$; $V_{DS} = 40\ V$; see Figure 14 ; see Figure 15	-	6.1	-	V
C_{iss}	input capacitance	$V_{DS} = 40\ V$; $V_{GS} = 0\ V$; $f = 1\ MHz$;	-	8161	-	pF
C_{oss}	output capacitance	$T_j = 25\ ^\circ C$; see Figure 16	-	701	-	pF
C_{rss}	reverse transfer capacitance		-	337	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 40\ V$; $R_L = 0.53\ \Omega$; $V_{GS} = 10\ V$;	-	38	-	ns
t_r	rise time	$R_{G(ext)} = 4.7\ \Omega$; $I_D = 75\ A$	-	29	-	ns
$t_{d(off)}$	turn-off delay time		-	94	-	ns
t_f	fall time		-	33	-	ns

Table 6. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 25\text{ A}$; $V_{GS} = 0\text{ V}$; $T_J = 25\text{ }^{\circ}\text{C}$; see Figure 17	-	0.8	1.2	V
t_{rr}	reverse recovery time	$I_S = 25\text{ A}$; $dI_S/dt = 100\text{ A}/\mu\text{s}$; $V_{GS} = 0\text{ V}$;	-	59	-	ns
Q_r	recovered charge	$V_{DS} = 20\text{ V}$	-	109	-	nC

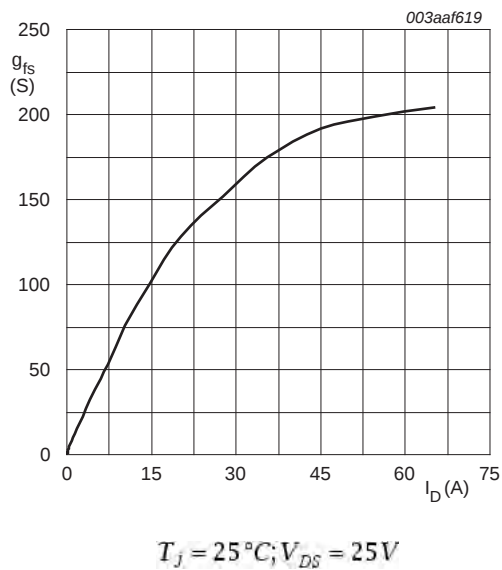


Fig 5. Forward transconductance as a function of drain current; typical values

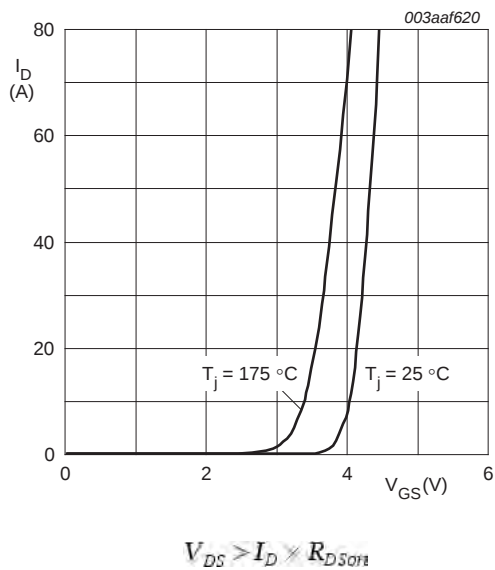


Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values

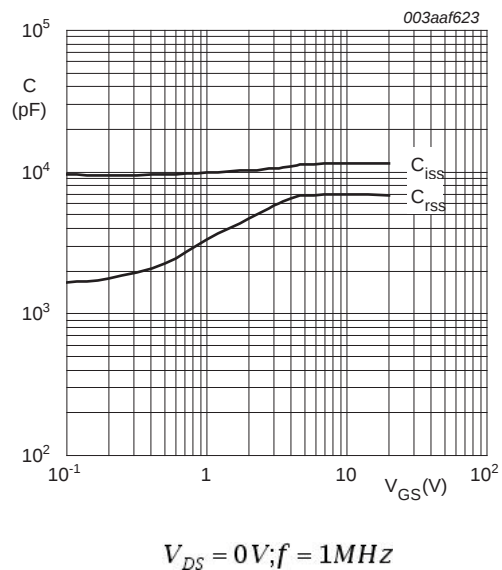


Fig 7. Input and reverse transfer capacitances as a function of gate-source voltage; typical values

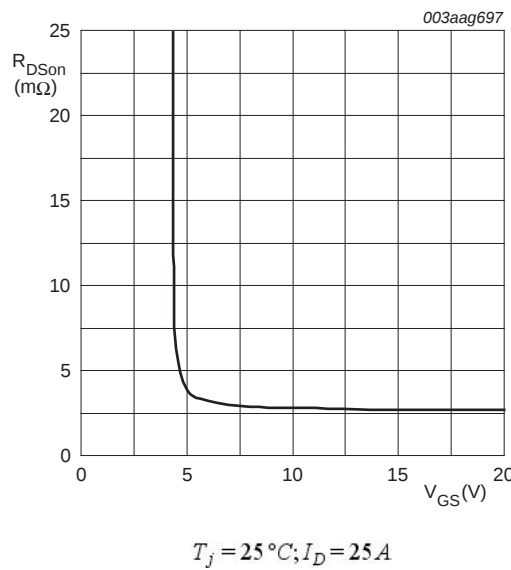


Fig 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

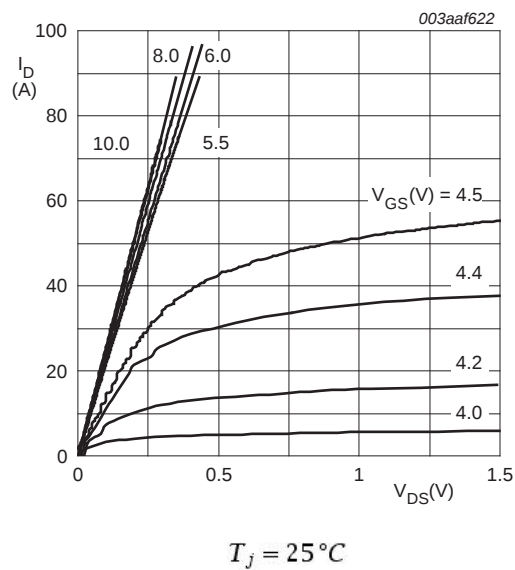


Fig 9. Output characteristics: drain current as a function of drain-source voltage; typical values

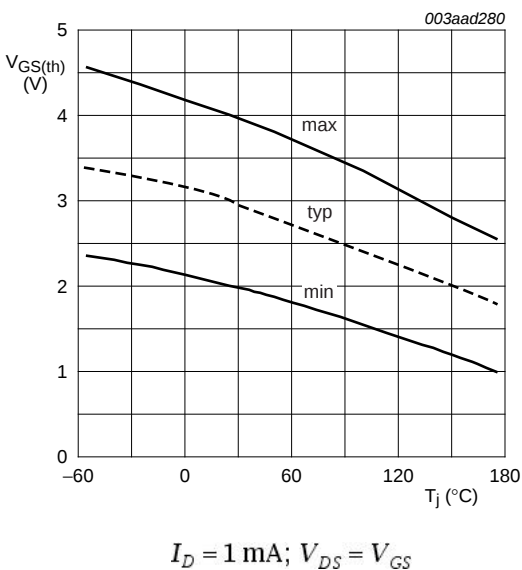


Fig 10. Gate-source threshold voltage as a function of junction temperature

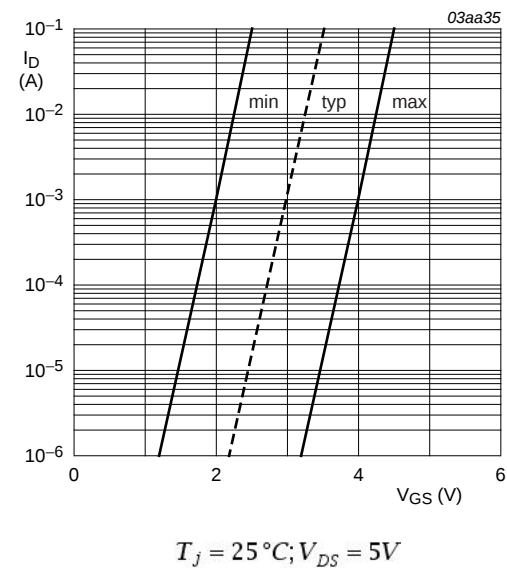


Fig 11. Sub-threshold drain current as a function of gate-source voltage

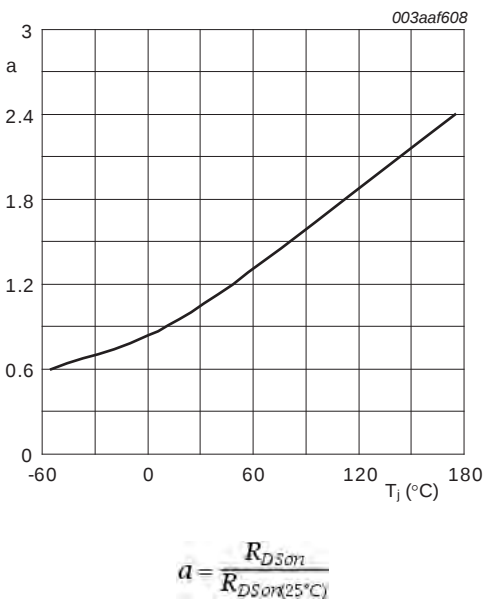
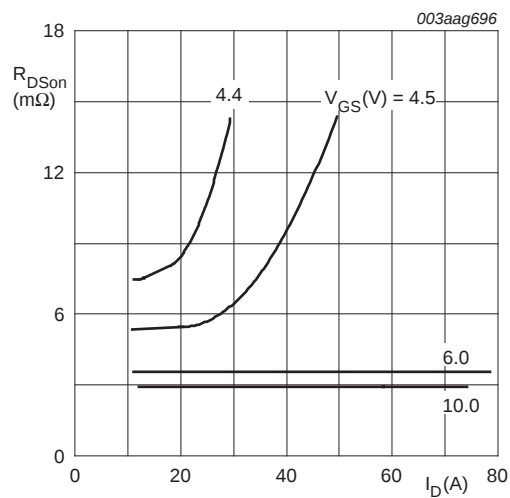


Fig 12. Normalized drain-source on-state resistance factor as a function of junction temperature



$T_j = 25^\circ\text{C}; I_D = 25\text{ A}$

Fig 13. Drain-source on-state resistance as a function of drain current; typical values

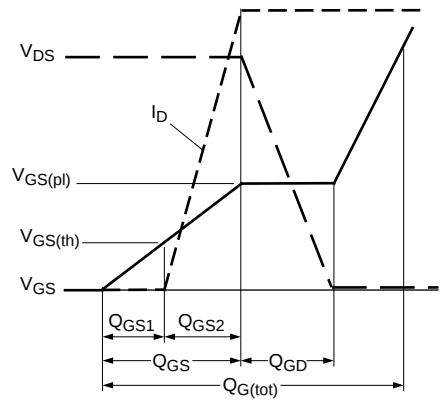
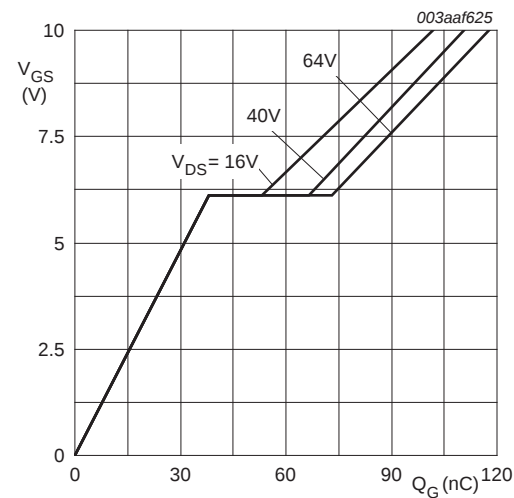
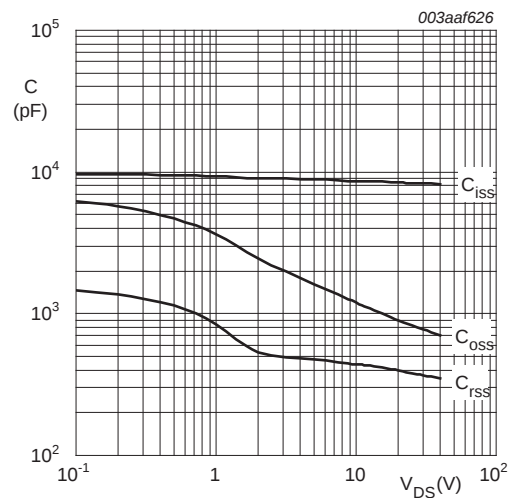


Fig 14. Gate charge waveform definitions



$I_D = 75\text{ A}$

Fig 15. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0\text{ V}; f = 1\text{ MHz}$

Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

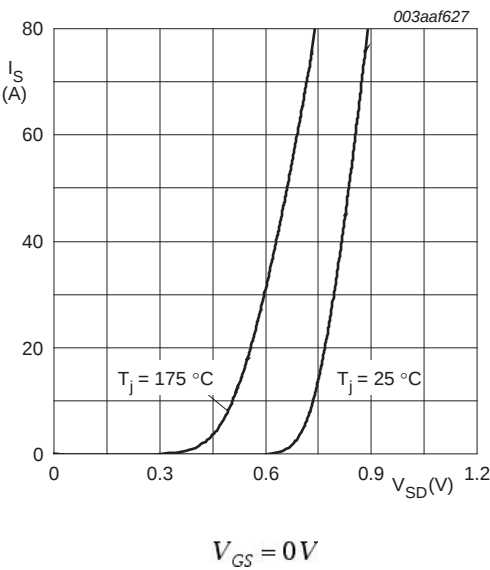
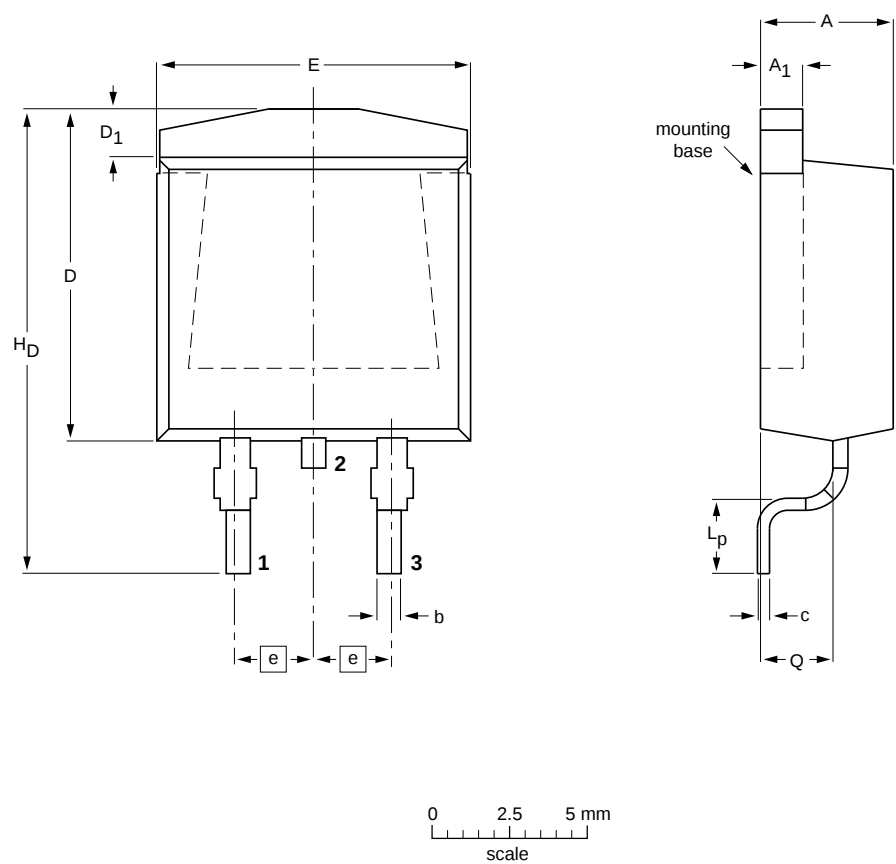


Fig 17. Source current as a function of source-drain voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

SOT404



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	c	D _{max.}	D ₁	E	e	L _p	H _D	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.80 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT404						05-02-11 06-03-16

Fig 18. Package outline SOT404 (D2PAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN3R3-80BS v.2	20120229	Product data sheet	-	PSMN3R3-80BS v.1
Modifications:	• Status changed from objective to product. • Various changes to content.			
PSMN3R3-80BS v.1	20110928	Objective data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 29 February 2012

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